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(12) United States Design Patent

Miller et al.

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(54) **SEMICONDUCTOR INTEGRATED CIRCUIT TEST HEAD**

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(**) Term: **14 Years**

(21) Appl. No.: **29/201,978**

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(51) **LOC (8) Cl.** **10-04**
(52) **U.S. Cl.** **D10/80**
(58) **Field of Search** D10/75, 78, 80, D10/102; 324/158.1, 756, 761–762; 439/68, 70, 912

(56) **References Cited**

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(57) **CLAIM**

The ornamental design for a semiconductor integrated circuit test head, as shown and described.

DESCRIPTION

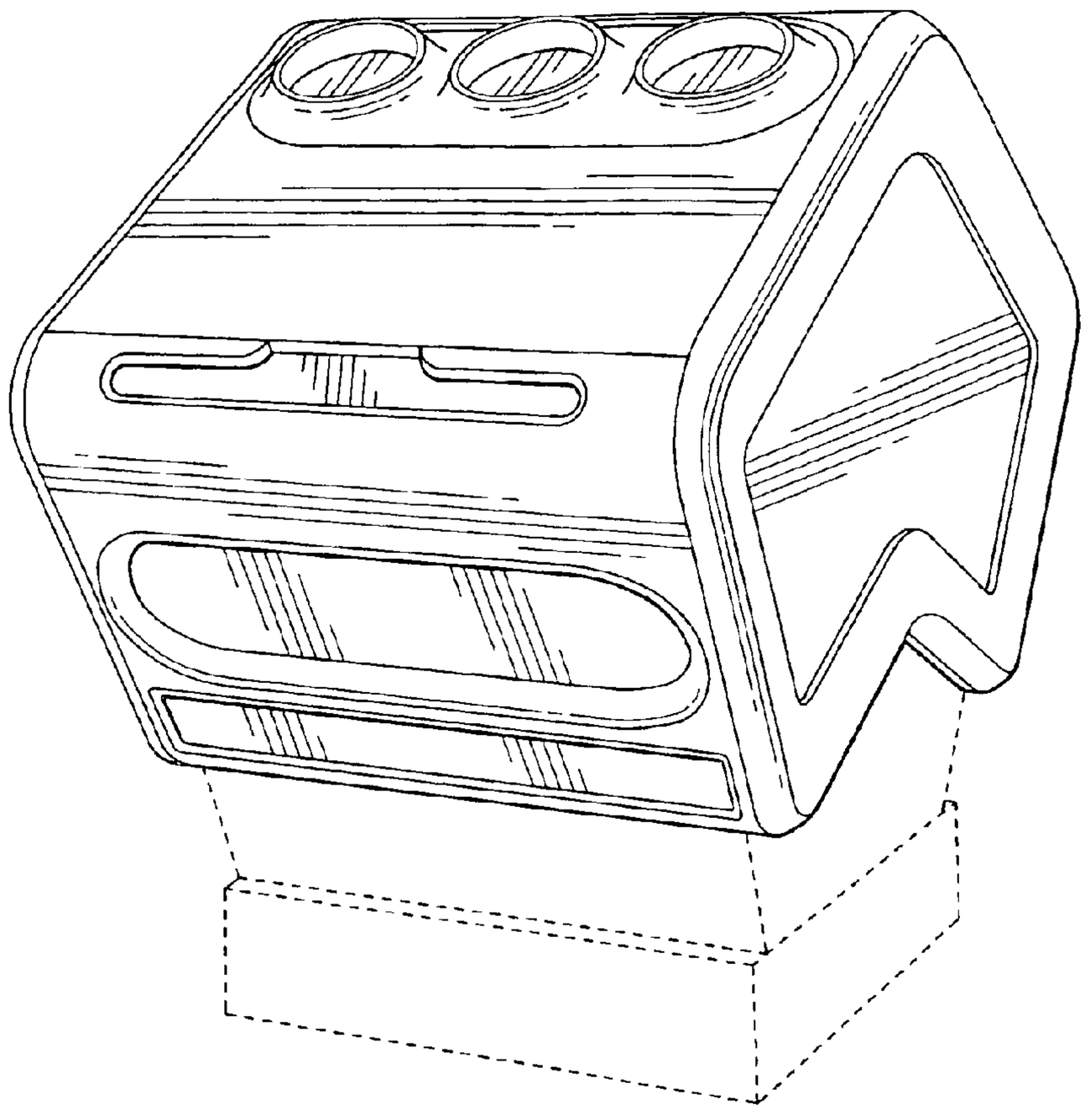
FIG. **1** is a perspective view of a semiconductor integrated circuit test head showing my new design,

FIG. **2** is an end elevation thereof, the opposite end elevation being of corresponding appearance,

FIG. **3** is a side elevation thereof; and,

FIG. **4** is a top plan view thereof.

1 Claim, 2 Drawing Sheets



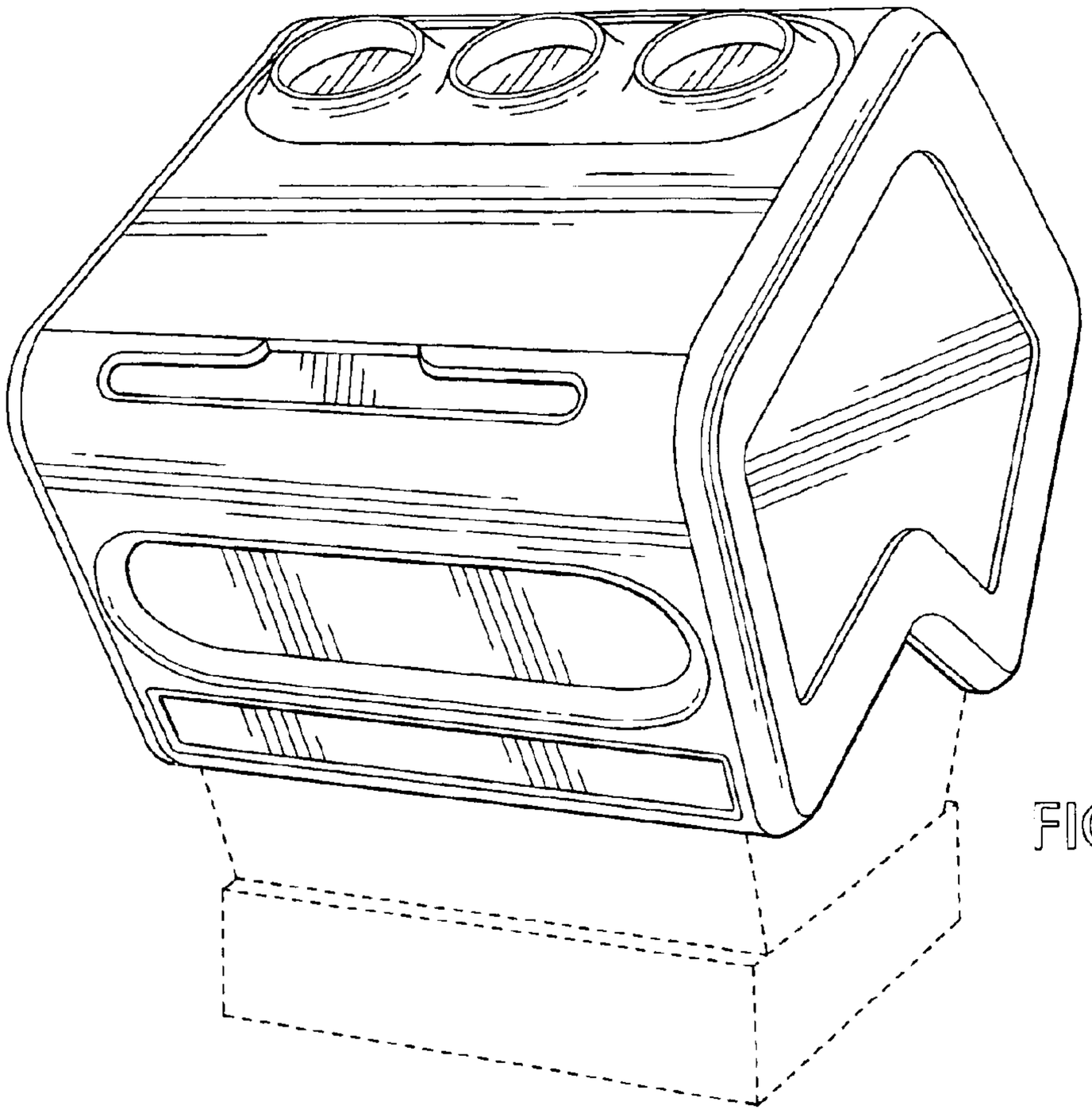


FIG.1

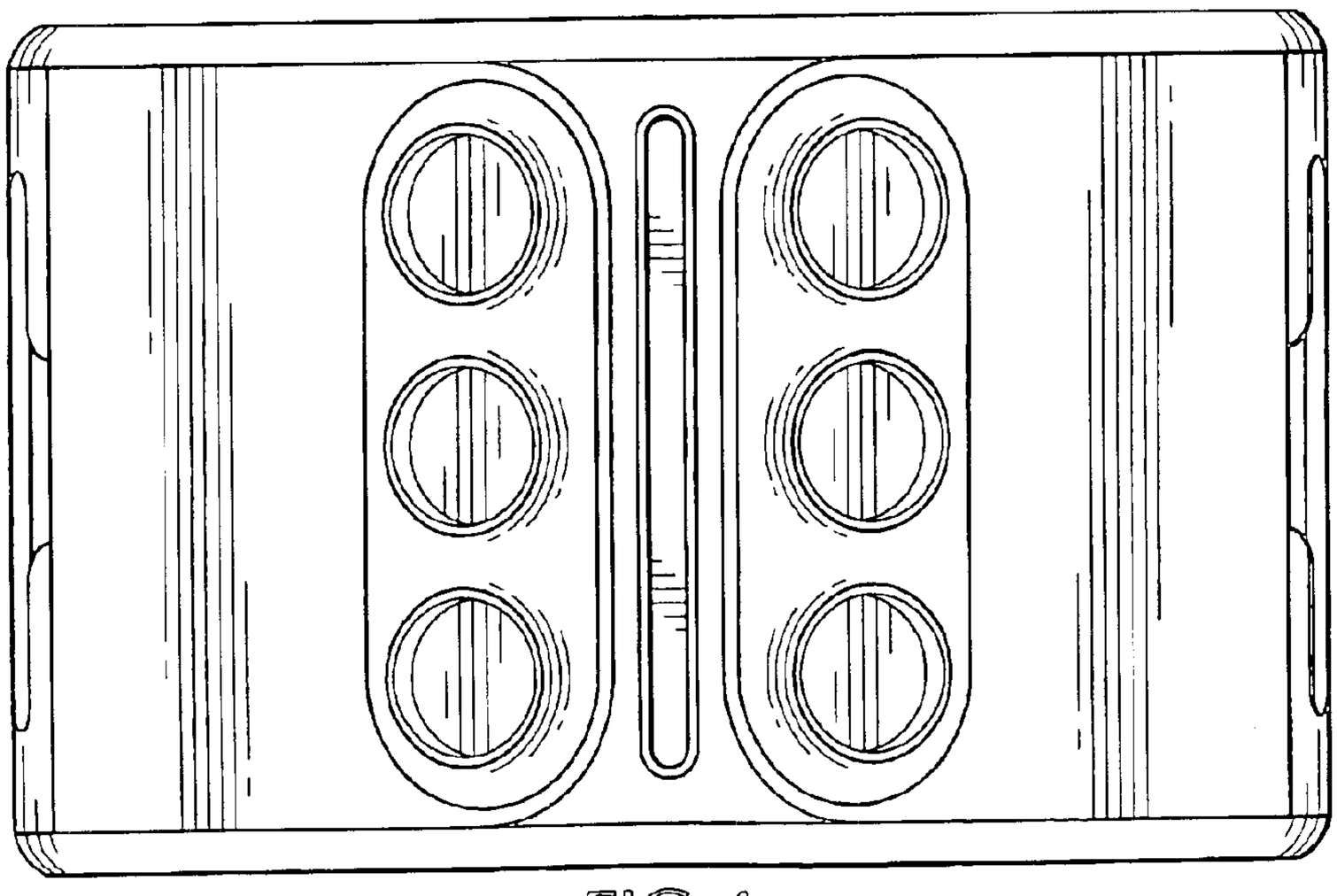


FIG.4

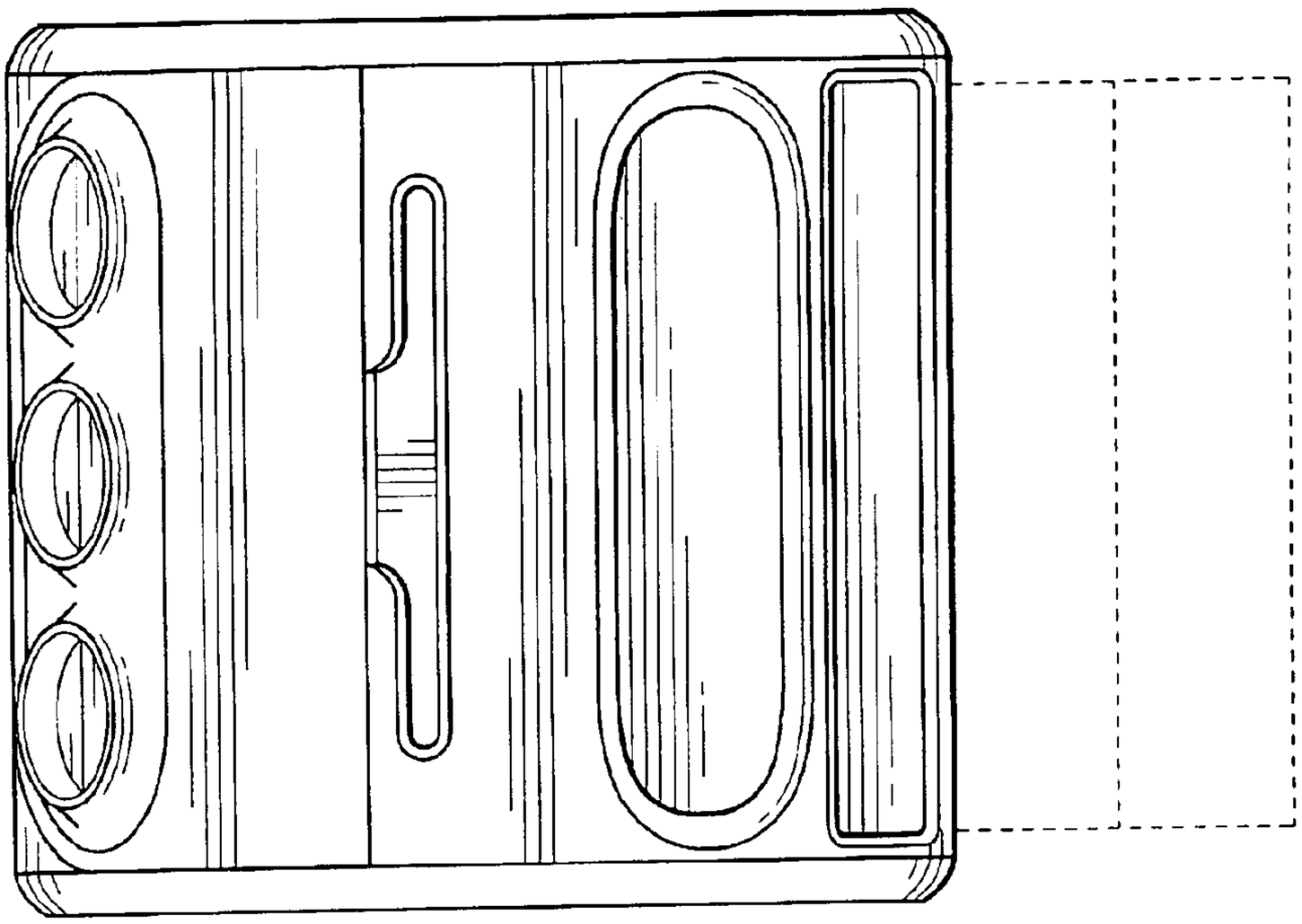


FIG.3

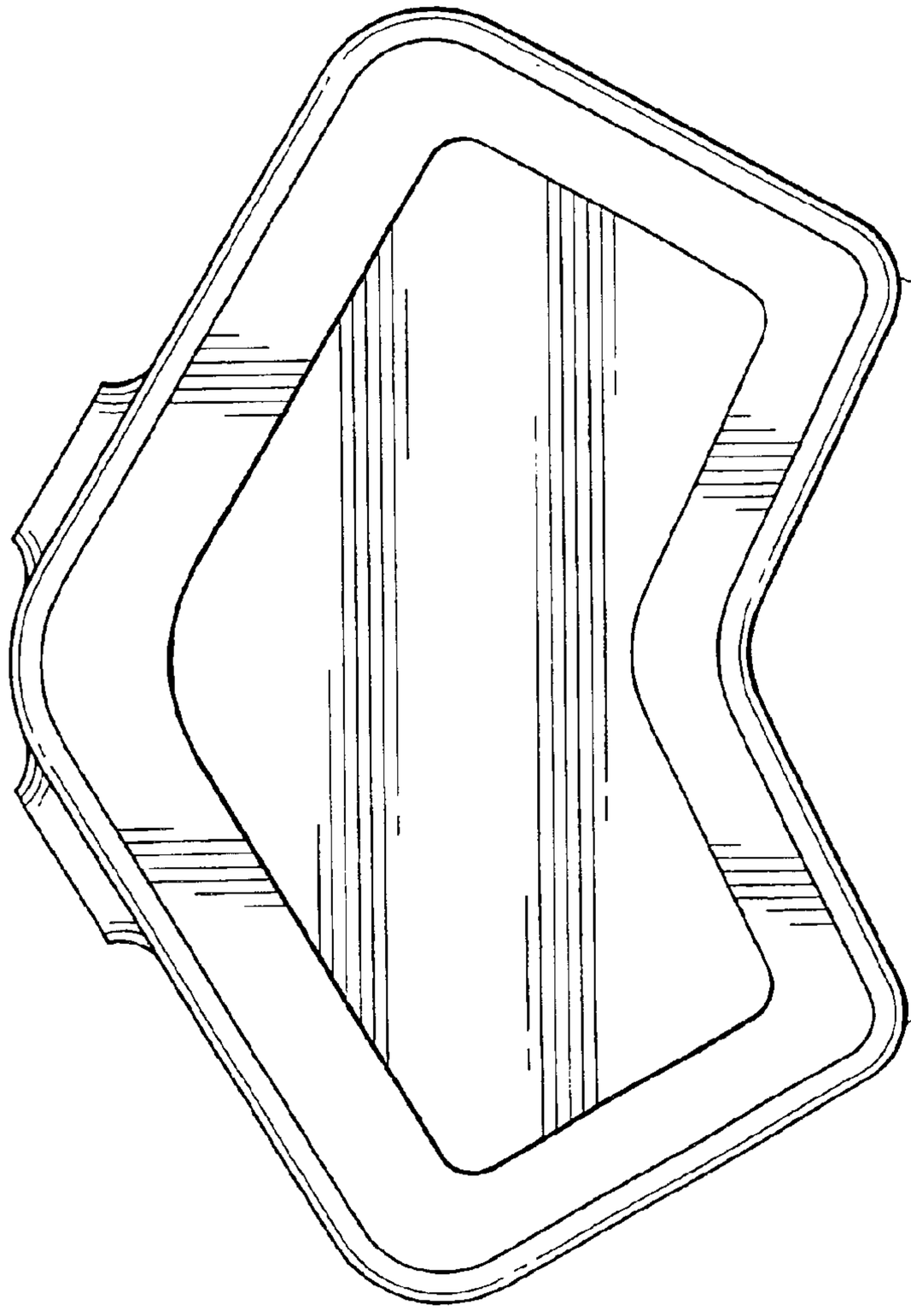


FIG.2